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Electronic Patent Application Submission  
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EFS ID: 63793

Application ID: 10826487



Title of Invention:

FORMATION OF PROTECTION  
LAYER BY DRIPPING DI ON WAFER  
WITH HIGH ROTATION TO  
PREVENT STAIN FORMATION  
FROM H2O2/H2SO4 CHEMICAL  
SPLASH

First Named Inventor: BO ZHENG

Domestic/Foreign Application: Domestic Application

Filing Date: 2004-04-16

Effective Receipt Date: 2004-07-01

Submission Type: Information Disclosure  
Statement

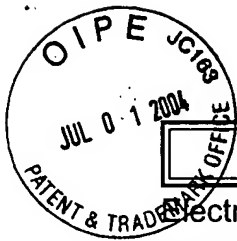
Filing Type:

Confirmation number: 1358

Attorney Docket Number: AMAT7589


Total Fees Authorized:

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Trademark Office,ou=Department of Commerce,o=U.S. Government,c=US  
Certificate Message Digest: 4c733f7c3cdb830e5fb56299fa0125e236328b1c

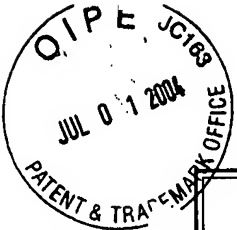


# TRANSMITTAL

Electronic Version v1.1  
Stylesheet Version v1.1.0

Title of Invention	FORMATION OF PROTECTION LAYER BY DRIPPING DI ON WAFER WITH HIGH ROTATION TO PREVENT STAIN FORMATION FROM H2O2/H2SO4 CHEMICAL SPLASH									
Application Number: 10/826487 										
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First Named Applicant: BO ZHENG										
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<p>I hereby certify that the use of this system is for OFFICIAL correspondence between patent applicants or their representatives and the USPTO. Fraudulent or other use besides the filing of official correspondence by authorized parties is strictly prohibited, and subject to a fine and/or imprisonment under applicable law.</p> <p>I, the undersigned, certify that I have viewed a display of document(s) being electronically submitted to the United States Patent and Trademark Office, using either the USPTO provided style sheet or software, and that this is the document(s) I intend for initiation or further prosecution of a patent application noted in the submission. This document(s) will become part of the official electronic record at the USPTO.</p>										
<table border="1"><thead><tr><th>Submitted by:</th><th>Elec. Sign.</th><th>Sign. Capacity</th></tr></thead><tbody><tr><td>Mr. N. ALEXANDER NOLTE Registered Number: 45689</td><td>[N. ALEXANDER NOLTE]</td><td>Attorney</td></tr></tbody></table>			Submitted by:	Elec. Sign.	Sign. Capacity	Mr. N. ALEXANDER NOLTE Registered Number: 45689	[N. ALEXANDER NOLTE]	Attorney		
Submitted by:	Elec. Sign.	Sign. Capacity								
Mr. N. ALEXANDER NOLTE Registered Number: 45689	[N. ALEXANDER NOLTE]	Attorney								
<table><tr><td>Documents being submitted</td><td>Files</td></tr><tr><td>us-ids</td><td>AMAT7589NAN-usidst.xml</td></tr><tr><td></td><td>us-ids.dtd</td></tr><tr><td></td><td>us-ids.xsl</td></tr></table>			Documents being submitted	Files	us-ids	AMAT7589NAN-usidst.xml		us-ids.dtd		us-ids.xsl
Documents being submitted	Files									
us-ids	AMAT7589NAN-usidst.xml									
	us-ids.dtd									
	us-ids.xsl									
Comments										

NO FEES DUE - FILED BEFORE 1ST OA



## ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

Stylesheet Version v18.0

### Title of Invention

FORMATION OF PROTECTION LAYER BY DRIPPING DI  
ON WAFER WITH HIGH ROTATION TO PREVENT STAIN  
FORMATION FROM H2O2/H2SO4 CHEMICAL SPLASH

Application Number: 10/826487



Confirmation Number: 1358

First Named Applicant: BO ZHENG

Attorney Docket Number: AMAT7589

Search string: ( 4557785 or 5022419 or 5095027 or 5154199  
or 5221360 or 5409310 or 6062239 or 6167893  
or 6199298 or 6217667 or 6240933 or 6286231  
or 6309981 or 6318385 or 6319841 or 6333275  
or 6350319 or 6357142 or 6401732 or 6413436  
or 6446643 or 6446644 or 6537416 or 6550484  
or 6558478 or 6615854 or 20020026729 ).pn.

### US Patent Documents

Note: Applicant is not required to submit a paper copy of cited US Patent Documents

init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
	1	4557785	1985-12-10	OHKUMA			
	2	5022419	1991-06-11	THOMPSON, ET AL.			
	3	5095027	1992-03-10	GOLDBERG, ET AL.			
	4	5154199	1992-10-13	THOMPSON, ET AL.			
	5	5221360	1993-06-22	THOMPSON, ET AL.			
	6	5409310	1995-04-25	OWCZARZ			
	7	6062239	2000-05-16	BEXTEN			
	8	6167893	2001-01-02	TAATJES, ET AL.			
	9	6199298	2001-03-13	BERGMAN			
	10	6217667	2001-04-17	JOLLEY			
	11	6240933	2001-06-05	BERGMAN			
	12	6286231	2001-09-11	BERGMAN, ET AL.			
	13	6309981	2001-10-30	MAYER, ET AL.			
	14	6318385	2001-11-20	CURTIS, ET AL.			

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	17	6350319	2002-02-26	CURTIS, ET AL.
	18	6357142	2002-03-19	BERGMAN, ET AL.
	19	6401732	2002-06-11	BERGMAN
	20	6413436	2002-07-02	AEGERTER, ET AL.
	21	6446643	2002-09-10	CURTIS, ET AL.
	22	6446644	2002-09-10	DOLECHEK
	23	6537416	2003-03-25	MAYER, ET AL.
	24	6550484	2003-04-22	GOPINATH, ET AL.
	25	6558478	2003-05-06	KATAKABE, ET AL.
	26	6615854	2003-09-09	HONGO, ET AL.

## US Published Applications

Note: Applicant is not required to submit a paper copy of cited US Published Applications

init	Cite.No.	Pub. No.	Date	Applicant	Kind	Class	Subclass
	1	20020026729	2002-03-07	BERGMAN, ET AL.			

## Remarks

Note: Remarks are not for responding to an office action.

NO FEES DUE - FILED BEFORE 1ST OA

## Signature

Examiner Name	Date